

/ Descriptions

Silicon PNP transistor in a TO-3P Plastic Package.

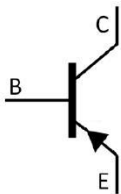
/ Features

For 45-50W audio frequency amplifier output stage, Complementary to 2SD718.

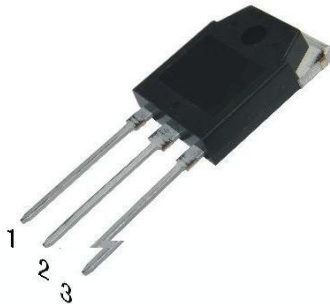
/ Applications

Designed for use in audio frequency amplifier.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Collector PIN 3 Emitter

/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	R	O
h_{FE} Range	55~110	80~160

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-120	V
Collector to Emitter Voltage	V_{CEO}	-120	V
Emitter to Base Voltage	V_{EBO}	-5	V
Collector Current - Continuous	I_C	-10	A
Base Current	I_B	-1	A
Collector Power Dissipation	$P_C(T_C=25^{\circ}C)$	80	W
Junction Temperature	T_j	150	$^{\circ}C$
Storage Temperature Range	T_{stg}	-55~150	$^{\circ}C$

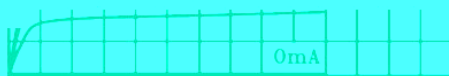
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=-50mA$ $I_B=0$	-120			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-120V$ $I_E=0$			-10	μA
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=-5.0V$ $I_C=0$			-10	μA
DC Current Gain	h_{FE}	$V_{CE}=-5.0V$ $I_C=-1.0A$	55		160	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=-5.0A$ $I_B=-0.5A$			-2.5	V
Base to Emitter Voltage	V_{BE}	$V_{CE}=-5.0V$ $I_C=-5.0A$			-1.5	V

$I_C - V_{CE}$

COMMON EMITTER
 $T_C = 25^\circ\text{C}$

$P_C - T_a$

① $T_a = T_c$
 INFINITE HEAT SINK
 ② 300x300x2mm Al
 HEAT SINK
 ③ 200x200x2mm Al
 HEAT SINK



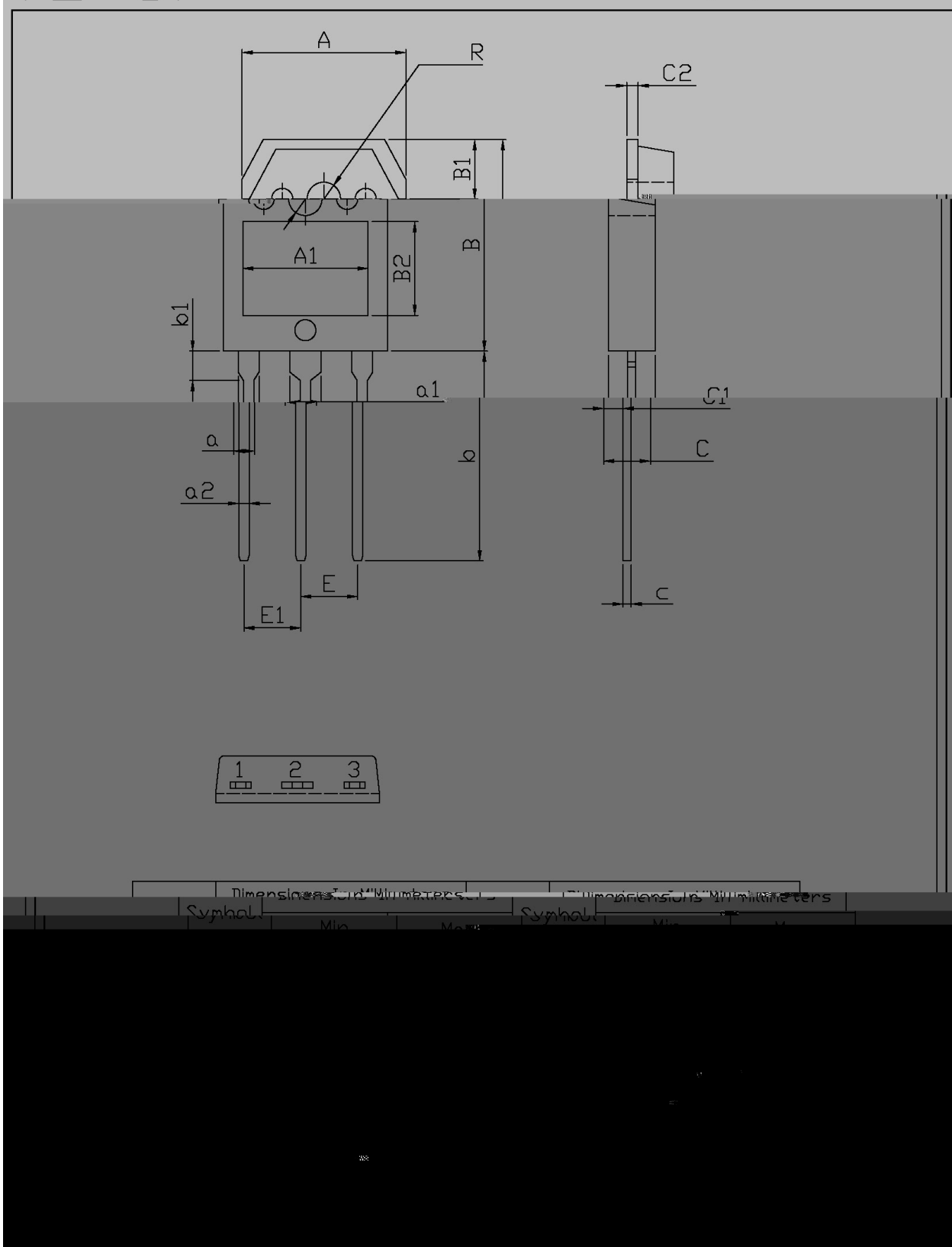
COMMON EMITTER

$$I_C = \text{MAX(PULSED)} \times$$

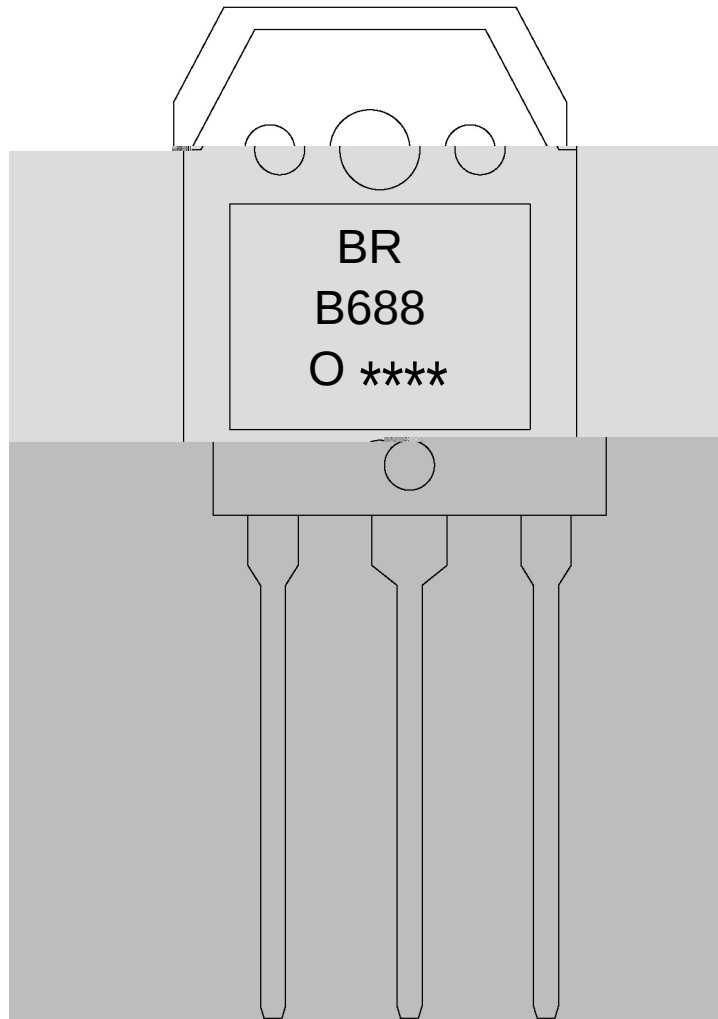
~~t=1ms ✖~~
~~t=10ms ✖~~

TU-3P

單位：



/ Marking Instructions



h_{FE}

Note:

BR: Company Code.

B688: Product Type.

O: h_{FE} Classifications Symbol.

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|---------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255 | 5 | 5 | 0.5sec; | 2.Peak Temp.:255 5 , Duration:5 0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270 5 10 1 sec. Temp.:270±5℃ Time:10±1 sec

/ Packaging SPEC.

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-3P	30	15	450	5	2250	497.5×46×8	555×164×50	575 290 180.3667 0 T04 JTT15 5